

Preliminary W27C4096



256K × 16 ELECTRICALLY ERASABLE EPROM

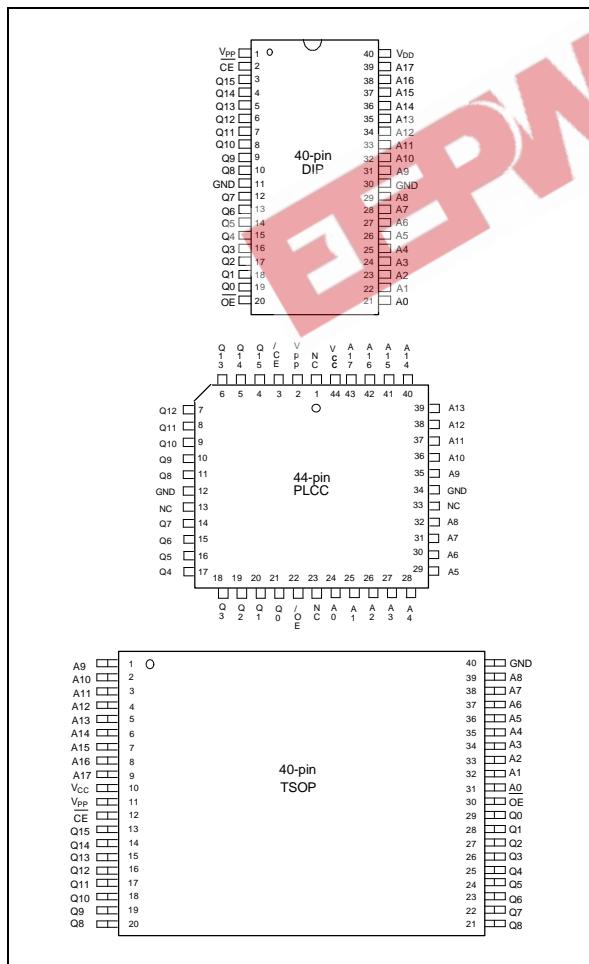
GENERAL DESCRIPTION

The W27C4096 is a high speed, low power Electrically Erasable and Programmable Read Only Memory organized as 262144×16 bits that operates on a single 5 volt power supply. The W27C4096 provides an electrical chip erase function.

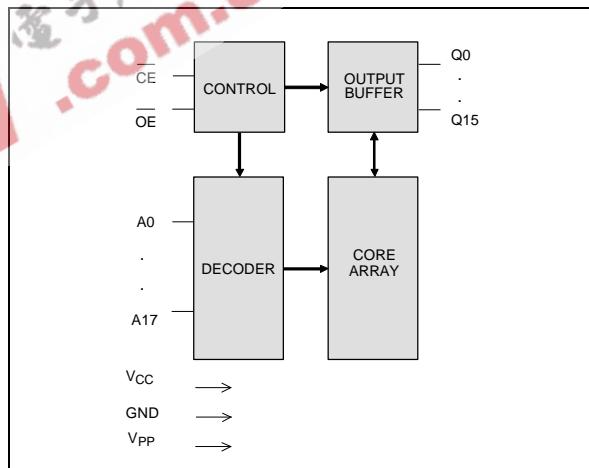
FEATURES

- High speed access time:
120/150 nS (max.)
- Read operating current: 30 mA (max.)
- Erase/Programming operating current
30 mA (max.)
- Standby current: 100 μ A (max.)
- Single 5V power supply
- +14V erase/+12V programming voltage
- Fully static operation
- All inputs and outputs directly TTL/CMOS compatible
- Three-state outputs
- Available packages: 40-pin 600 mil DIP, TSOP and 44-pin PLCC

PIN CONFIGURATIONS



BLOCK DIAGRAM



PIN DESCRIPTION

SYMBOL	DESCRIPTION
A0–A17	Address Inputs
Q0–Q15	Data Inputs/Outputs
CE	Chip Enable
OE	Output Enable
V _{PP}	Program/Erase Supply Voltage
V _{CC}	Power Supply
GND	Ground
NC	No Connection

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FUNCTIONAL DESCRIPTION

Read Mode

Like conventional UVEPROMs, the W27C4096 has two control functions, both of which produce data at the outputs. \overline{CE} is for power control and chip select. \overline{OE} controls the output buffer to gate data to the output pins. When addresses are stable, the address access time (TACC) is equal to the delay from \overline{CE} to output (TCE), and data are available at the outputs TOE after the falling edge of \overline{OE} , if TACC and TCE timings are met.

Erase Mode

The erase operation is the only way to change data from "0" to "1." Unlike conventional UVEPROMs, which use ultraviolet light to erase the contents of the entire chip (a procedure that requires up to half an hour), the W27C4096 uses electrical erasure. Generally, the chip can be erased within 100 mS by using an EPROM writer with a special erase algorithm.

Erase mode is entered when VPP is raised to VPE (14V), $V_{CC} = V_{CE}$ (5V), \overline{CE} low, \overline{OE} high, A9 = VPE (14V), A0 low, and all other address pins low and data input pins high.

Erase Verify Mode

After an erase operation, all of the words in the chip must be verified to check whether they have been successfully erased to "1" or not. The erase verify mode automatically ensures a substantial erase margin. This mode will be entered after the erase operation if $V_{PP} = V_{PE}$ (14V), \overline{CE} high, and \overline{OE} low.

Program Mode

Programming is performed exactly as it is in conventional UVEPROMs, and programming is the only way to change cell data from "1" to "0." The program mode is entered when VPP is raised to VPP (12V), $V_{CC} = V_{CP}$ (5V), \overline{CE} low, \overline{OE} high, the address pins equal the desired address, and the input pins equal the desired inputs.

Program Verify Mode

All of the words in the chip must be verified to check whether they have been successfully programmed with the desired data or not. Hence, after each word is programmed, a program verify operation should be performed. The program verify mode automatically ensures a substantial program margin. This mode will be entered after the program operation if $V_{PP} = V_{PP}$ (12V), \overline{CE} high, OE low and $V_{CC} = V_{CP}$ (5V).

Erase/Program Inhibit

Erase or program inhibit mode allows parallel erasing or programming of multiple chips with different data. When \overline{CE} high, $V_{PP} = V_{PP}/V_{PE}$ (12V/14V), and $V_{CC} = 5V$, erasing or programming of non-target chips is inhibited, so that except for the \overline{CE} and V_{PP} , and V_{CC} , the W27C4096 may have common inputs.

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Standby Mode

The standby mode significantly reduces Vcc current. This mode is entered when \overline{CE} high, $V_{PP} = 5V$, and $V_{CC} = 5V$. In standby mode, all outputs are in a high impedance state, independent of OE .

Two-line Output Control

Since EPROMs are often used in large memory arrays, the W27C4096 provides two control inputs for multiple memory connections. Two-line control provides for lowest possible memory power dissipation and ensures that data bus contention will not occur.

System Considerations

EPROM power switching characteristics require careful device decoupling. System designers are interested in three supply current issues: standby current levels (I_{SB}), active current levels (I_{CC}), and transient current peaks produced by the falling and rising edges of \overline{CE} . Transient current magnitudes depend on the device output's capacitive and inductive loading. Two-line control and proper decoupling capacitor selection will suppress transient voltage peaks. Each device should have a $0.1 \mu F$ ceramic capacitor connected between its V_{CC} and GND . This high frequency, low inherent-inductance capacitor should be placed as close as possible to the device. Additionally, for every eight devices, a $4.7 \mu F$ electrolytic capacitor should be placed at the array's power supply connection between V_{CC} and GND . The bulk capacitor will overcome voltage slumps caused by PC board trace inductances.

TABLE OF OPERATING MODES

($V_{PP} = 12V$, $V_{PE} = 14V$, $V_{HH} = 12V$, $V_{CP} = 5V$, X = V_{IH} or V_{IL})

MODE	PINS						
	\overline{CE}	OE	A_0	A_9	V_{CC}	V_{PP}	OUTPUTS
Read	V_{IL}	V_{IL}	X	X	V_{CC}	V_{CC}	D_{OUT}
Output Disable	V_{IL}	V_{IH}	X	X	V_{CC}	V_{CC}	High Z
Standby (TTL)	V_{IH}	X	X	X	V_{CC}	V_{CC}	High Z
Standby (CMOS)	$V_{CC} \pm 0.3V$	X	X	X	V_{CC}	V_{CC}	High Z
Program	V_{IL}	V_{IH}	X	X	V_{CP}	V_{PP}	D_{IN}
Program Verify	V_{IH}	V_{IL}	X	X	V_{CP}	V_{PP}	D_{OUT}
Program Inhibit	V_{IH}	X	X	X	V_{CP}	V_{PP}	High Z
Erase	V_{IL}	V_{IH}	V_{IL}	V_{PE}	V_{CE}	V_{PE}	D_{IH}
Erase Verify	V_{IH}	V_{IL}	X	X	V_{CE}	V_{PE}	D_{OUT}
Erase Inhibit	V_{IH}	X	X	X	V_{CE}	V_{PE}	High Z
Product Identifier-manufacturer	V_{IL}	V_{IL}	V_{IL}	V_{HH}	V_{CC}	V_{CC}	00DA (Hex)
Product Identifier-device	V_{IL}	V_{IL}	V_{IH}	V_{HH}	V_{CC}	V_{CC}	000D (Hex)

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DC CHARACTERISTICS

Absolute Maximum Ratings

PARAMETER	RATING	UNIT
Ambient Temperature with Power Applied	-55 to +125	°C
Storage Temperature	-65 to +125	°C
Voltage on all pins with Respect to Ground Except VPP, A9 and Vcc pins	-0.5 to Vcc +0.5	V
Voltage on VPP Pin with Respect to Ground	-0.5 to +14.5	V
Voltage on A9 Pin with Respect to Ground	-0.5 to +14.5	V
Voltage on Vcc Pin with Respect to Ground	-0.5 to +7	V

Note: Exposure to conditions beyond those listed under Absolute Maximum Ratings may adversely affect the life and reliability of the device.

DC Erase Characteristics

(TA = 25° C ±5° C, Vcc = 5.0V ± 5%, VHH = 14V)

PARAMETER	SYM.	CONDITIONS	LIMITS			UNIT
			MIN.	TYP.	MAX.	
Input Load Current	I _{LI}	V _{IN} = V _{IL} or V _{IH}	-10	-	10	µA
Vcc Erase Current	I _{CP}	CE = V _{IL}	-	-	30	mA
VPP Erase Current	I _{PP}	CE = V _{IL}	-	-	30	mA
Input Low Voltage	V _{IL}	-	-0.3	-	0.8	V
Input High Voltage	V _{IH}	-	2.4	-	5.5	V
Output Low Voltage (Verify)	V _{OL}	I _{OL} = 2.1 mA	-	-	0.45	V
Output High Voltage (Verify)	V _{OH}	I _{OH} = -0.4 mA	2.4	-	-	-
A9 Erase Voltage	V _{ID}	-	13.75	14	14.25	V
VPP Erase Voltage	V _{PE}	-	13.75	14	14.25	V
Vcc Supply Voltage (Erase)	V _{CE}	-	4.5	5.0	5.5	V

Note: Vcc must be applied simultaneously or before VPP and removed simultaneously or after VPP.

CAPACITANCE

(Vcc = 5V, TA = 25° C, f = 1 MHz)

PARAMETER	SYMBOL	CONDITIONS	MAX.	UNIT
Input Capacitance	C _{IN}	V _{IN} = 0V	6	pF
Output Capacitance	C _{OUT}	V _{OUT} = 0V	12	pF

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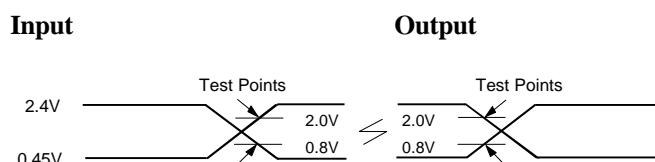
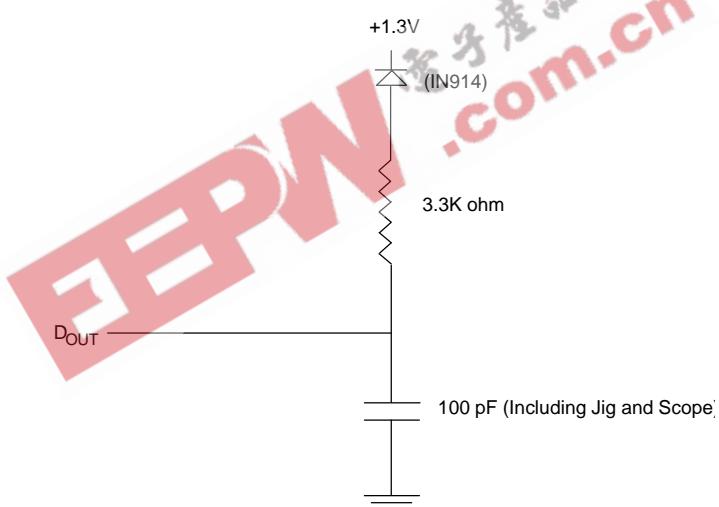


AC CHARACTERISTICS

AC Test Conditions

PARAMETER	CONDITIONS
Input Pulse Levels	0.45V to 2.4V
Input Rise and Fall Times	10 nS
Input and Output Timing Reference Level	0.8V/2.0V
Output Load	CL = 100 pF, IOH/IOL = -0.4 mA/2.1 mA

AC Test Load and Waveform



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READ OPERATION DC CHARACTERISTICS

(Vcc = 5.0V ±5%, TA = 0 to 50° C)

PARAMETER	SYM.	CONDITIONS	LIMITS			UNIT
			MIN.	TYP.	MAX.	
Input Load Current	ILI	VIN = 0V to Vcc	-5	-	5	µA
Output Leakage Current	ILO	VOUT = 0V to Vcc	-10	-	10	µA
Vcc Standby Current	ISB	CĒ = VIH	-	-	1.0	mA
	ISB1	CĒ = Vcc ±0.2V	-	5	100	µA
Vcc Operating Current	ICC	CĒ = VIL IOUT = 0 mA, f = 5 MHz	-	-	30	mA
VPP Operating Current	IPP	VPP = VCC	-	-	10	µA
Input Low Voltage	VIL	-	-0.3	-	0.8	V
Input High Voltage	VIH	-	2.2	-	Vcc +0.5	V
Output Low Voltage	VOL	IOL = 2.1 mA	-	-	0.4	V
Output High Voltage	VOH	IOH = -0.4 mA	2.4	-	-	V
VPP Operating Voltage	VPP	-	Vcc -0.7	-	Vcc	V

READ OPERATION AC CHARACTERISTICS

(Vcc = 5.0V ±5%, TA = 0 to 50° C)

PARAMETER	SYM.	W27C4096-12		W27C4096-15		UNIT
		MIN.	MAX.	MIN.	MAX.	
Read Cycle Time	TRC	120	-	150	-	nS
Chip Enable Access Time	TCE	-	120	-	150	nS
Address Access Time	TACC	-	120	-	150	nS
Output Enable Access Time	TOE	-	50	-	70	nS
OĒ High to High-Z Output	TDF	-	30	-	30	nS
Output Hold from Address Change	TOH	0	-	0	-	nS

Note: Vcc must be applied simultaneously or before VPP and removed simultaneously or after VPP.

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DC PROGRAMMING CHARACTERISTICS

(V_{CC} = 5.0V ±5%, T_A = 25° C ±5° C)

PARAMETER	SYM.	CONDITIONS	LIMITS			UNIT
			MIN.	TYP.	MAX.	
Input Load Current	I _{LI}	V _{IN} = V _{IL} or V _{IH}	-10	-	10	µA
V _{CC} Program Current	I _{CP}	CĒ = V _{IL}	-	-	30	mA
V _{PP} Program Current	I _{PP}	CĒ = V _{IL}	-	-	30	mA
Input Low Voltage	V _{IL}	-	-0.3	-	0.8	V
Input High Voltage	V _{IH}	-	2.4	-	5.5	V
Output Low Voltage (Verify)	V _{OL}	I _{OL} = 2.1 mA	-	-	0.45	V
Output High Voltage (Verify)	V _{OH}	I _{OH} = -0.4 mA	2.4	-	-	V
A9 Silicon I.D. Voltage	V _{ID}	-	11.5	12.0	12.5	V
V _{PP} Program Voltage	V _{PP}	-	11.75	12.0	12.25	V
V _{CC} Supply Voltage (Program)	V _{CP}	-	4.5	5.0	5.5	V

AC PROGRAMMING/ERASE CHARACTERISTICS

(V_{CC} = 5.0V ±5%, T_A = 25° C ±5° C)

PARAMETER	SYM.	LIMITS			UNIT
		MIN.	TYP.	MAX.	
V _{PP} Setup Time	T _{VPS}	2.0	-	-	µS
Address Setup Time	T _{AS}	2.0	-	-	µS
Data Setup Time	T _{DSS}	2.0	-	-	µS
CĒ Program Pulse Width	T _{WPW}	95	100	105	µS
CĒ Erase Pulse Width	T _{WEW}	95	100	105	µS
Data Hold Time	T _{DH}	2.0	-	-	µS
OĒ Setup Time	T _{OES}	2.0	-	-	µS
Data Valid from OĒ	T _{OEV}	-	-	150	nS
OĒ High to Output High Z	T _{DFF}	0	-	130	nS
Address Hold Time	T _{AH}	0	-	-	µS
Address Hold Time after CĒ High (Erase)	T _{AHC}	2.0	-	-	µS

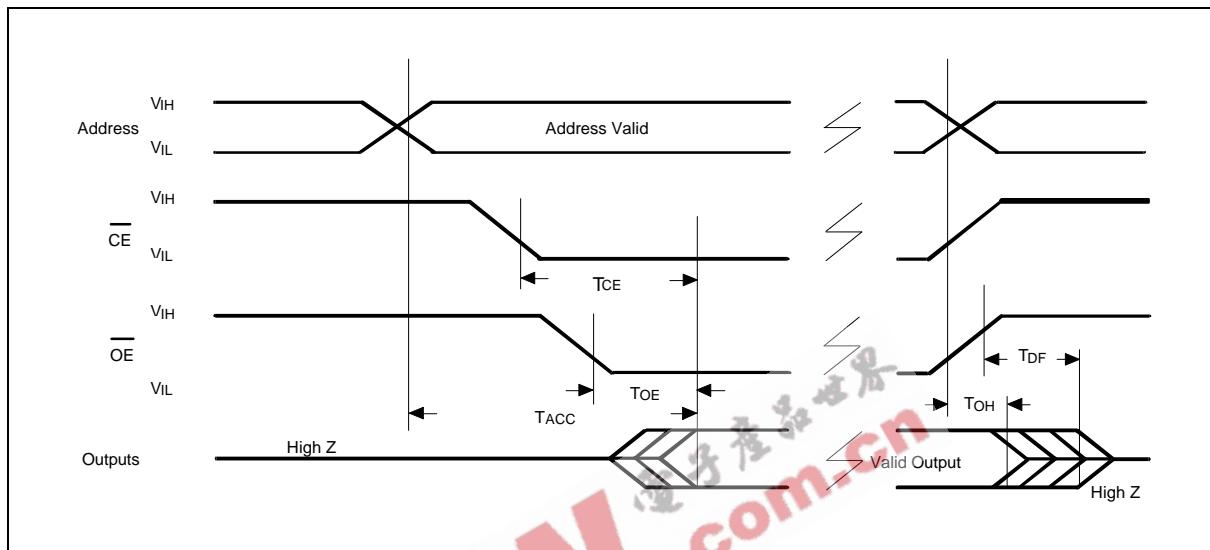
Note: V_{CC} must be applied simultaneously or before V_{PP} and removed simultaneously or after V_{PP}.

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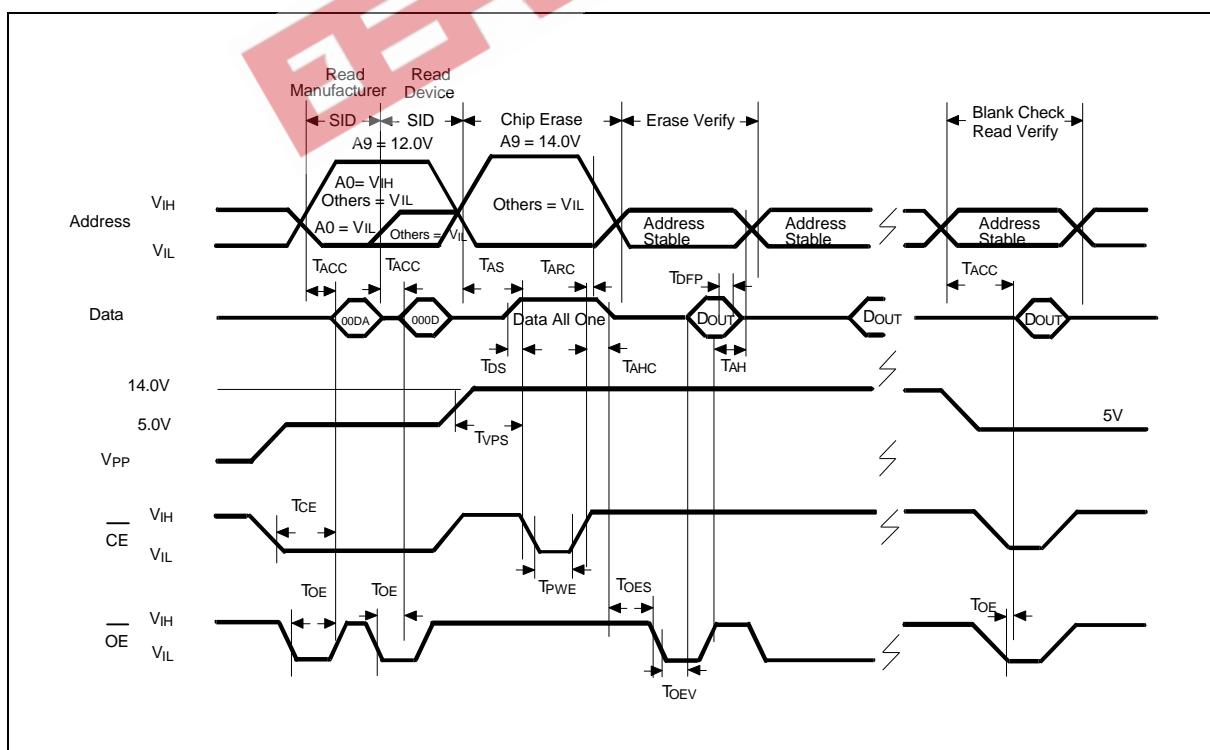


TIMING WAVEFORMS

AC Read Waveform



Erase Waveform

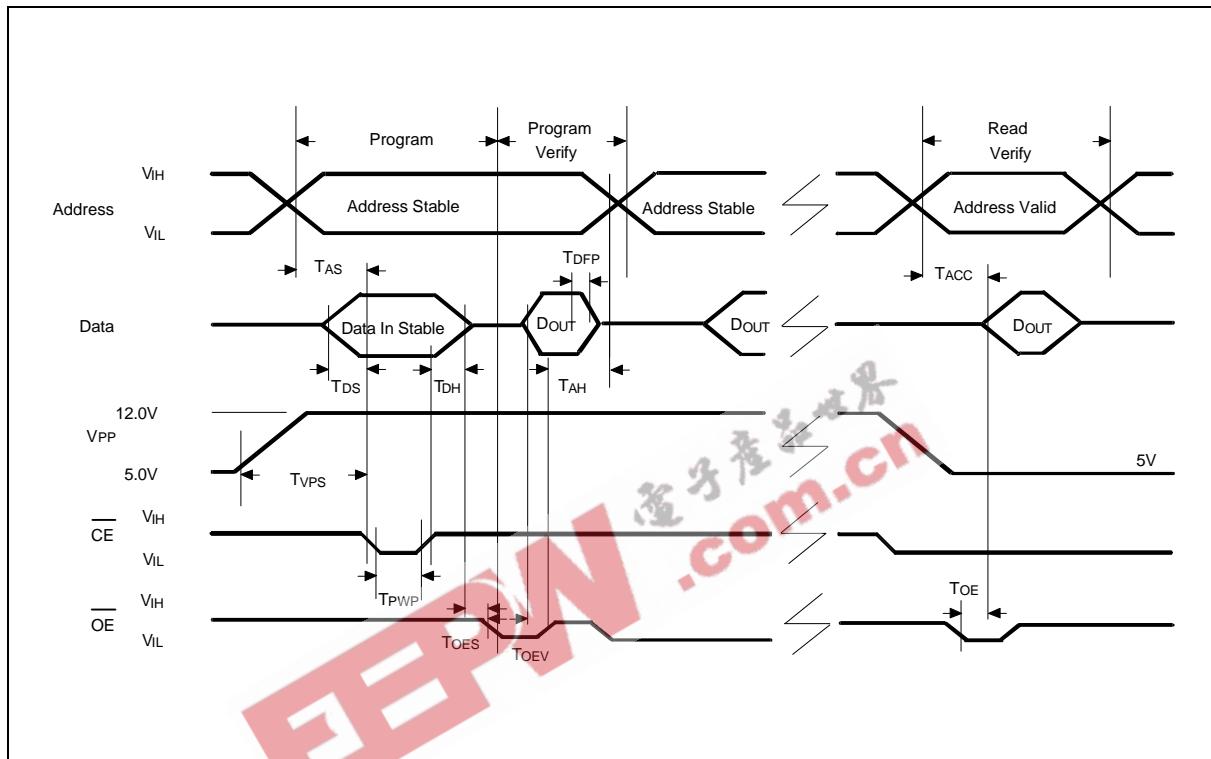


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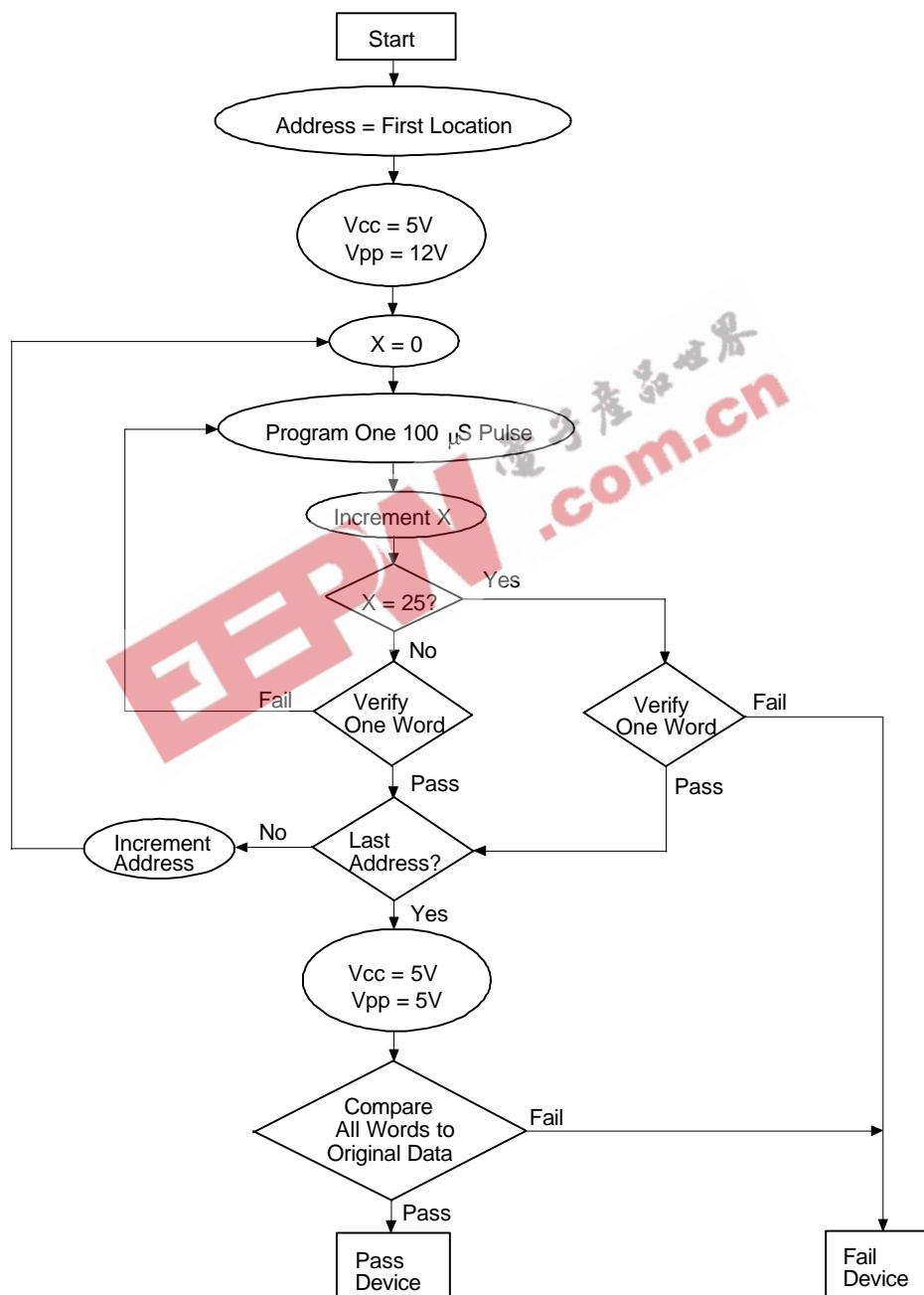
Timing Waveforms, continued

Programming Waveform





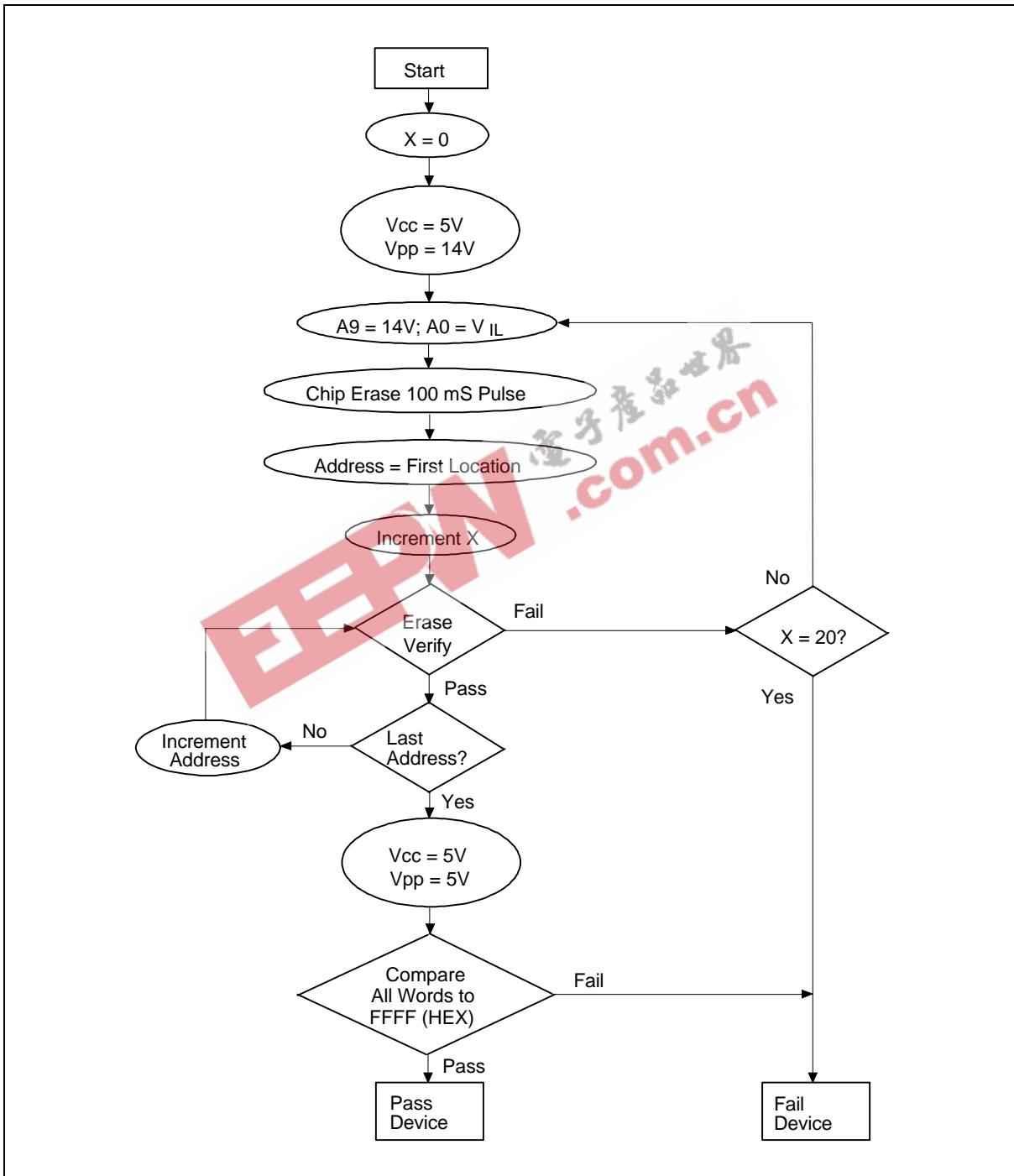
SMART PROGRAMMING ALGORITHM



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SMART ERASE ALGORITHM



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ORDERING INFORMATION

PART NO.	ACCESS TIME (nS)	POWER SUPPLY CURRENT MAX. (mA)	STANDBY Vcc CURRENT MAX. (mA)	PACKAGE
W27C4096-12	120	30	100	600 mil DIP
W27C4096T-12	120	30	100	40-pin TSOP
W27C4096P-12	120	30	100	44-pin PLCC
W27C4096-15	150	30	100	600 mil DIP
W27C4096T-15	150	30	100	40-pin TSOP
W27C4096P-15	150	30	100	44-pin PLCC

Notes:

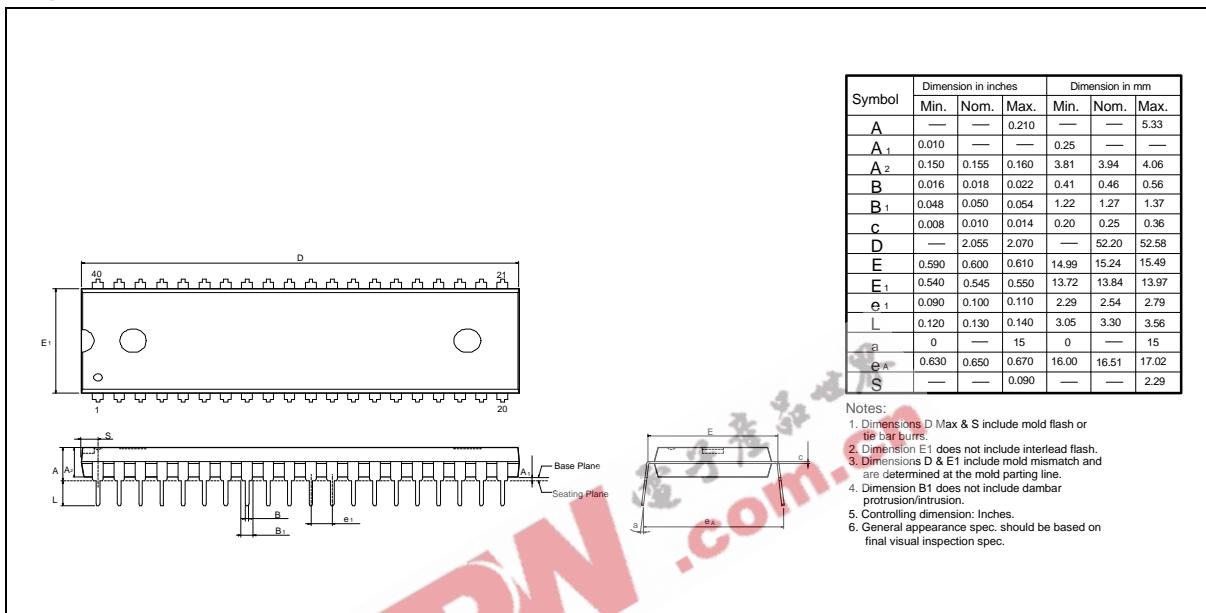
1. Winbond reserves the right to make changes to its products without prior notice.
2. Purchasers are responsible for performing appropriate quality assurance testing on products intended for use in applications where personal injury might occur as a consequence of product failure.

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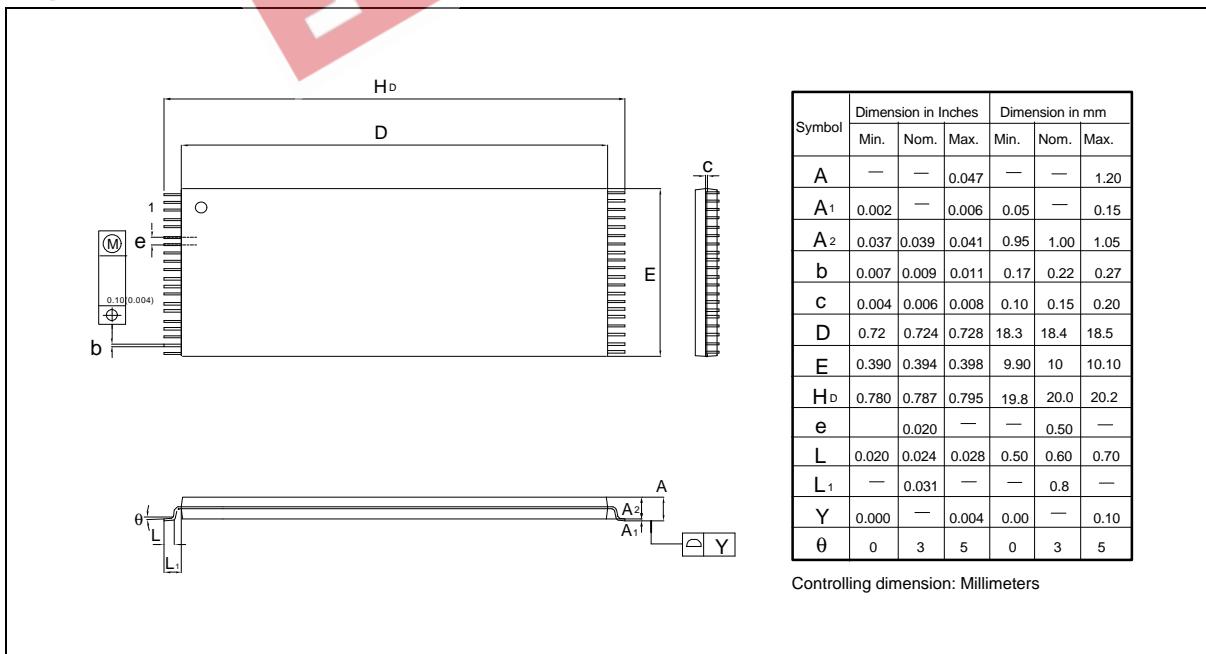


PACKAGE DIMENSIONS

40-pin PDIP



40-pin TSOP

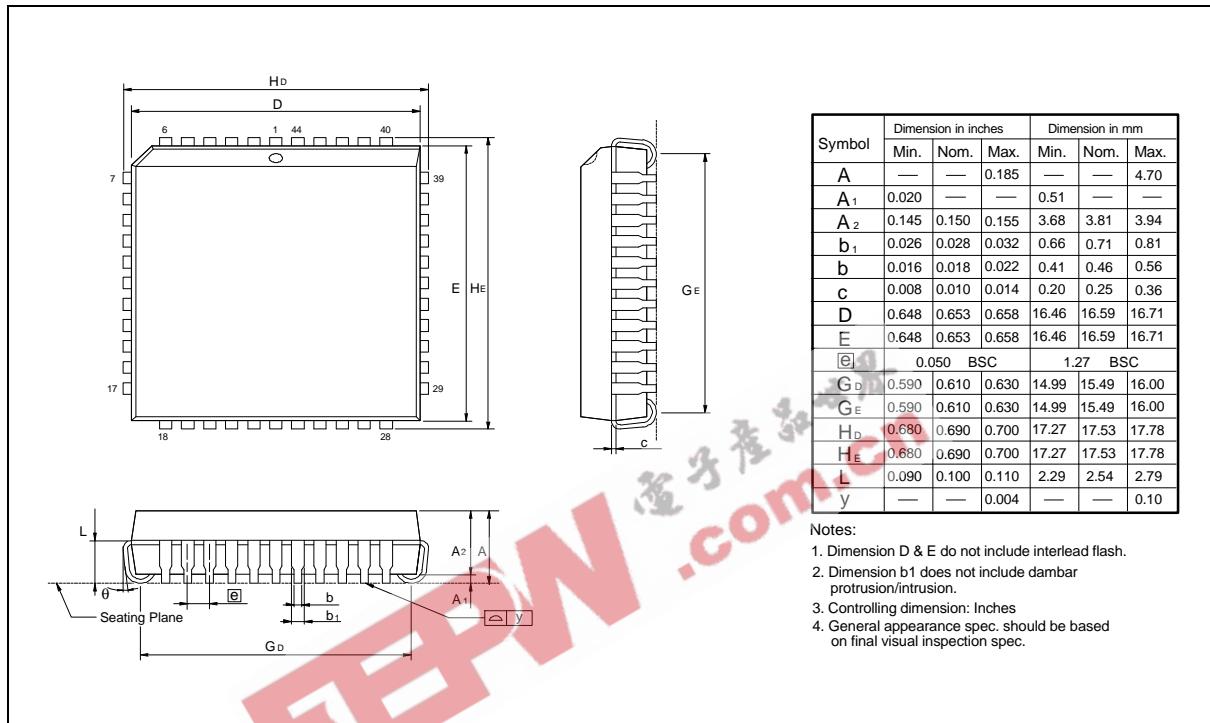


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Package Dimensions, continued

44-pin PLCC



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VERSION HISTORY

VERSION	DATE	PAGE	DESCRIPTION
A1	Mar. 1999		Initial Issued

EEBN.com.cn



Headquarters

No. 4, Creation Rd. III,
Science-Based Industrial Park,
Hsinchu, Taiwan
TEL: 886-3-5770066
FAX: 886-3-5796096
<http://www.winbond.com.tw/>
Voice & Fax-on-demand: 886-2-7197006

Taipei Office

11F, No. 115, Sec. 3, Min-Sheng East Rd.,
Taipei, Taiwan
TEL: 886-2-7190505
FAX: 886-2-7197502

Winbond Electronics (H.K.) Ltd.

Rm. 803, World Trade Square, Tower II,
123 Hoi Bun Rd., Kwun Tong,
Kowloon, Hong Kong
TEL: 852-27513100
FAX: 852-27552064

Winbond Electronics North America Corp.

Winbond Memory Lab.
Winbond Microelectronics Corp.
Winbond Systems Lab.
2727 N. First Street, San Jose,
CA 95134, U.S.A.
TEL: 408-9436666
FAX: 408-5441798

Note: All data and specifications are subject to change without notice.

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Revision A1